

Krit Athikulwongse

List of Publications by Year in descending order

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Version: 2024-02-01

12
papers

102
citations

1937685

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h-index

2053705

5
g-index

12
all docs

12
docs citations

12
times ranked

108
citing authors

#	ARTICLE	IF	CITATIONS
1	Improved Step Detection with Smartphone Handheld Mode Recognition. , 2021, , .		1
2	Mapping the Physical and Dielectric Properties of Layered Soil Using Short-Time Matrix Pencil Method-Based Ground-Penetrating Radar. IEEE Access, 2020, 8, 105610-105621.	4.2	7
3	High Performance Application Specific Stream Architecture for Hardware Acceleration of HOG-SVM on FPGA. IEICE Transactions on Fundamentals of Electronics, Communications and Computer Sciences, 2019, E102.A, 1792-1803.	0.3	0
4	Automatic Detection and Classification of Buried Objects Using Ground-Penetrating Radar for Counter-Improvised Explosive Devices. Radio Science, 2018, 53, 210-227.	1.6	17
5	Implication of anchor placement on performance of UWB real-time locating system. , 2017, , .		9
6	Investigation of the electrical property of multi-layer soil using short-time matrix pencil method. , 2017, , .		3
7	Fast bidirectional shortest path on GPU. IEICE Electronics Express, 2016, 13, 20160036-20160036.	0.8	1
8	On performance study of UWB real time locating system. , 2016, , .		29
9	On study of an impulse RADAR sensor for subsurface object detection. , 2015, , .		3
10	Exploiting Die-to-Die Thermal Coupling in 3-D IC Placement. IEEE Transactions on Very Large Scale Integration (VLSI) Systems, 2014, 22, 2145-2155.	3.1	14
11	Impact of Mechanical Stress on the Full Chip Timing for Through-Silicon-Via-based 3-D ICs. IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems, 2013, 32, 905-917.	2.7	14
12	Block-level designs of die-to-wafer bonded 3D ICs and their design quality tradeoffs. , 2013, , .		4